

**Supplementary information**

Temperature Self-Compensation Thin Film Strain Gauges Based on nano-SiO<sub>2</sub>/AgNPs Composite

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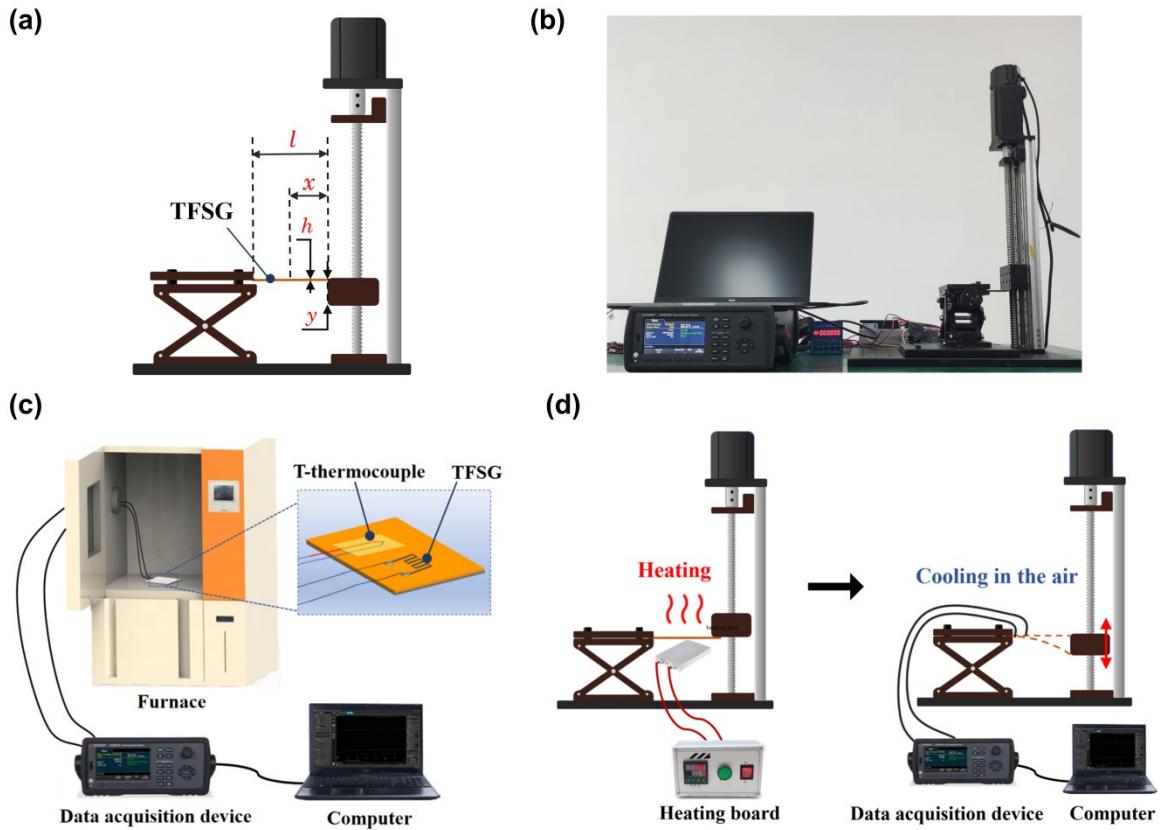
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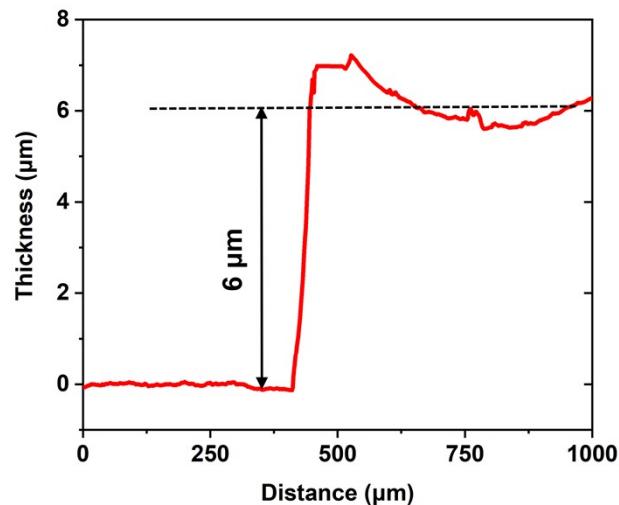
**Table S1** Performance comparison of the sensor with near-zero-TCR strain sensors prepared by functional ink reported in the literature.

| Sensor Materials                  | Substrate                      | Process                   | Curing temperature of sensor materials (°C) | Maximum detectable strain (micro-strain is underline) | GF          | TCR (ppm /°C) | Ref              |
|-----------------------------------|--------------------------------|---------------------------|---|---|-------------|---------------|------------------|
| Silver/carbon                     | PET                            | screen-printed            | 130   | <u>0.08%</u>  | 7.7         | Unclear       | 1                |
| SWCNT/graphite                    | PET                            | spray coating             | 90  | <u>0.16%</u>  | 5.0         | Unclear       | 2                |
| GNPs/Polysilazane                 | Al <sub>2</sub> O <sub>3</sub> | Direct ink writing        | 500   | <u>0.04%</u>  | 19.1        | -3.7          | 3                |
| AgNWs/graphene                    | PDMS                           | Drop coating              | 90  | 40%   | 80          | 160           | 4                |
| AgNPs/CNT                         | Silicone                       | Drop coating              | 60  | 100%  | 38.2        | -11.6         | 5                |
| MWCNT/graphene                    | Polyimide                      | Drop coating              | Room temperature                            | Unclear   | 16.2        | Unclear       | 6                |
| graphene/CNT/silicone             | -                              | Direct ink writing        | Room temperature                            | 100%  | 10.7        | 114           | 7                |
| P3HT/BCF/AgNPs                    | Polyimide                      | Spin coating              | 80  | 6.1%  | 64          | 1100          | 8                |
| PEDOT:PSS/DMSO                    | PET                            | Spin coating              | 120   | 2%  | 1.9         | 93            | 9                |
| AgNPs                             | PET                            | Spin coating              | Unclear                                     | 1%  | 51          | 19            | 10               |
| <b>Nano-SiO<sub>2</sub>/AgNPs</b> | <b>Alloy steel</b>             | <b>Direct ink writing</b> | <b>150</b>                                  | <b><u>0.2%</u></b>                                    | <b>16.4</b> | <b>30</b>     | <b>This work</b> |

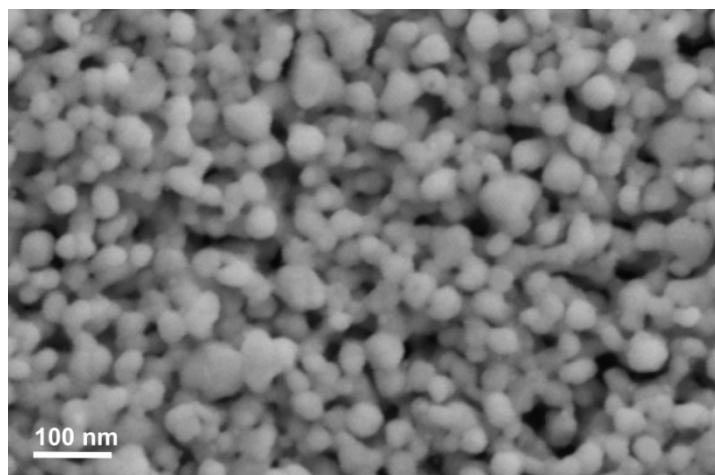
PET: polyethylene terephthalate, SWCNT: single-wall carbon nanotube, GNPs: graphite nanoplatelets, AgNWs: silver nanowires, PDMS: polydimethylsiloxane, AgNPs: silver nanoparticles, CNT: carbon nanotubes, MWCNT: multi-walled carbon nanotubes, P3HT: poly(3-hexylthiophene-2,5-diyl), BCF: tris(pentafluorophenyl)borane, PEDOT: poly(3,4-ethylenedioxythiophene), PSS: poly(styrenesulfonate), DMSO: dimethyl sulfoxide



**Fig. S1.** (a) Experiment setup for strain response detection. (b) Platform for strain testing and acquisition. (c) Experiment setup for temperature-resistance detection. (d) Experiment setup for dynamic response detection under variable temperature environments.



**Fig. S2.** The thickness of PI insulation film is close to 6  $\mu\text{m}$ .



**Fig. S3.** SEM image of AgNPs thin films.

## References

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